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**SIST EN 16603-20-08:2023**

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**Vesoljska tehnika - Fotonapetostni sestavi in komponente**

Space engineering - Photovoltaic assemblies and components

Raumfahrttechnik - Fotovoltaische Baugruppen und Komponenten

Ingénierie spatiale - Ensembles et composants photovoltaïque

**Ta slovenski standard je istoveten z: EN 16603-20-08:2023**

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## Space engineering - Photovoltaic assemblies and components

Ingénierie spatiale - Ensembles et composants  
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Komponenten

This European Standard was approved by CEN on 23 July 2023.

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**CEN-CENELEC Management Centre:  
Rue de la Science 23, B-1040 Brussels**

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## European foreword

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This document (EN 16603-20-08:2023) has been prepared by Technical Committee CEN-CENELEC/TC 5 “Space”, the secretariat of which is held by DIN.

This standard (EN 16603-20-08:2023) originates from ECSS-E-ST-20-08C Rev.2.

This European Standard shall be given the status of a national standard, either by publication of an identical text or by endorsement, at the latest by March 2024, and conflicting national standards shall be withdrawn at the latest by March 2024.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN [and/or CENELEC] shall not be held responsible for identifying any or all such patent rights.

This document supersedes EN 16603-20-08:2014.

The main changes with respect to EN 16603-20-08:2014 are listed below:

- Implementation of change requests
- Addition of new clause 12 “Planar Blocking Diodes”
- Check and update of the use of the verb “define” in the document

This document has been prepared under a standardization request given to CEN by the European Commission and the European Free Trade Association. [SIST EN 16603-20-08:2023](https://standards.iteh.ai/catalog/standards/sist/b01b880c-150a-4aa1-b1f5-10442bc39737/sist-en-16603-20-08-2023)

This document has been developed to cover specifically space systems and has therefore precedence over any EN covering the same scope but with a wider domain of applicability (e.g. : aerospace).

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